

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Seung June YI</td><td>04/25/2011</td></tr><tr><td>Sung Duck CHUN</td><td>04/25/2011</td></tr><tr><td>Sung Hoon JUNG</td><td>04/25/2011</td></tr><tr><td>Young Dae LEE</td><td>04/25/2011</td></tr><tr><td>Sung Jun PARK</td><td>04/25/2011</td></tr></tbody></table>	Name	Execution Date	Seung June YI	04/25/2011	Sung Duck CHUN	04/25/2011	Sung Hoon JUNG	04/25/2011	Young Dae LEE	04/25/2011	Sung Jun PARK	04/25/2011	
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<table border="1"><tr><td>Name:</td><td>LG ELECTRONICS INC.</td></tr><tr><td>Street Address:</td><td>20 Yeouido-dong, Yeongdeungpo-gu</td></tr><tr><td>City:</td><td>Seoul</td></tr><tr><td>State/Country:</td><td>REPUBLIC OF KOREA</td></tr><tr><td>Postal Code:</td><td>150-721</td></tr></table>	Name:	LG ELECTRONICS INC.	Street Address:	20 Yeouido-dong, Yeongdeungpo-gu	City:	Seoul	State/Country:	REPUBLIC OF KOREA	Postal Code:	150-721			
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PROPERTY NUMBERS Total: 1													
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CORRESPONDENCE DATA													
Fax Number: (703)205-8050 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
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ATTORNEY DOCKET NUMBER:	5438-0216PUS1												
NAME OF SUBMITTER:	Esther H. Chong												
Total Attachments: 4 source=2011-05-03 - Assignment - 5438-0216PUS1#page1.tif source=2011-05-03 - Assignment - 5438-0216PUS1#page2.tif source=2011-05-03 - Assignment - 5438-0216PUS1#page3.tif source=2011-05-03 - Assignment - 5438-0216PUS1#page4.tif													

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PATENT  
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**BIRCH, STEWART, KOLASCH & BIRCH, LLP**UNITED STATES PATENT RIGHTS, OR  
UNITED STATES PLUS ALL FOREIGN PATENT RIGHTS**ASSIGNMENT**Application No. 13/095,810 Filed April 27, 2011Insert Name(s)  
of Inventor(s)

\*\*\* (Given Name FAMILY NAME (ALL CAPS)) \*\*\*

WHEREAS, Seung June YI, Sung Duck CHUN, Sung Hoon JUNG, Young Dae LEE and Sung Jun PARK (hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in:

Insert Title  
of Invention**APPARATUS AND METHOD OF PERFORMING MINIMIZATION OF DRIVE TESTS**

for which an application for Letters Patent of the United States of America has been executed by the undersigned (except in the case of a provisional application)

Insert Date  
of Signing of  
Application  
Insert Name  
of Assignee  
Insert Address  
of AssigneeOn April 25, 2011; and

WHEREAS, LG ELECTRONICS INC.

of 20 Yeouido-dong, Yeongdeungpo-gu, Seoul, 150-721 Republic of Korea

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America and

CHECK BOX  
IF APPROPRIATE☐ in any foreign countries.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned has (have) sold, assigned and transferred, and by these presents does sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and if the box above is designated, in any and all foreign countries; and to any and all divisions, reissues, continuations, conversions and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division, conversion or reissue thereof or Letter Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of Birch, Stewart, Kolasch & Birch, LLP the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

The undersigned hereby covenant(s) that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date <u>25-04-2011</u>	Name of Inventor <u>Seung June YI</u> (signature) Seung June YI
Date _____	Name of Inventor _____ (signature) Sung Duck CHUN
Date <u>25-04-2011</u>	Name of Inventor <u>Sung Hoon Jung</u> (signature) Sung Hoon JUNG
Date <u>25-04-2011</u>	Name of Inventor <u>Young Dae Lee</u> (signature) Young Dae LEE
Date <u>25-04-2011</u>	Name of Inventor <u>Sung Jun Park</u> (signature) Sung Jun PARK

# BIRCH, STEWART, KOLASCH & BIRCH, LLP

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Insert Address of Assignee of 20 Yeouido-dong, Yeongdeungpo-gu, Seoul, 150-721 Republic of Korea

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Date _____,	Name of Inventor _____ (signature) <b>Seung June YI</b>
Date <u>Apr-25-2011</u> ,	Name of Inventor _____ (signature) <b>Sung Duck CHUN</b> <i>[Signature]</i>
Date _____,	Name of Inventor _____ (signature) <b>Sung Hoon JUNG</b>
Date _____,	Name of Inventor _____ (signature) <b>Young Dae LEE</b>
Date _____,	Name of Inventor _____ (signature) <b>Sung Jun PARK</b>